

Product / Process Change Notification



N° 2018-045-A

Correction

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Several Changes affecting Gen5N Mosfets in D2PAK, DPAK packages

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **28. July 2020**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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► **Products affected:** Please refer to attached affected product list 1_cip18045_n

► **Detailed Change Information:**

Subject: Change of wafer production and wafer test location from Infineon Technologies Temecula to EPISIL Taiwan and additional assembly site at TFME China for for Gen5N Mosfets in D2PAK, DPAK packages

Reason: The wafer production and test of the affected products will be transferred to EPISIL Taiwan according to the global Infineon production strategy and Expansion of assembly production to assure continuity of supply and enable flexible manufacturing.

Description:	<u>Old</u>	<u>New</u>
Wafer Site	<ul style="list-style-type: none">■ Infineon Technologies Temecula	<ul style="list-style-type: none">■ Infineon Technologies Temecula and EPISIL Taiwan
Wafer Material	<ul style="list-style-type: none">■ Back Metal Cr-Ni-Ag■ Top Metal AlSi	<ul style="list-style-type: none">■ Ti-Ni-Ag■ AlSiCu
Assembly	<ul style="list-style-type: none">■ Infineon Tijuana	<ul style="list-style-type: none">■ Infineon Tijuana and TFME China
Assembly Material	<ul style="list-style-type: none">■ Nickel plated leadframe (except die pad)■ D2pak Die Attach= Pb-Ag-In	<ul style="list-style-type: none">■ Bare Copper leadframe (except tpost)■ D2Pak Die Attach= Pb-Sn-Ag
Testing	<ul style="list-style-type: none">■ Tesec	<ul style="list-style-type: none">■ Tesec and GRET
Marking	<ul style="list-style-type: none">■ No site code	<ul style="list-style-type: none">■ M site code

► **Product Identification:** Traceability assured via Lot number and date code.

► **Impact of Change:** No impact on electrical performance expected. Quality and reliability verified by qualification. There is no change in form, fit and function.

DeQuMa Ids: SEM-PW-06, SEM-PW-07, SEM-PW-13, SEM-PA-04, SEM-PA-13, SEM-PA-18, SEM-EQ-03, SEM-TF-01

► **Attachments:** Affected product list 1_cip18045_n

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► Time Schedule:

- | | |
|-------------------------------|------------------------|
| ■ Final qualification report: | Available upon request |
| ■ First samples available: | upon request |
| ■ Intended start of delivery: | 15-Dec-2020 |

If you have any questions, please do not hesitate to contact your local Sales office.

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Sales name	SP number	OPN	Package
AUIRFR024N	SP001515958	AUIRFR024N	PG-TO252-3
AUIRFR024NTRL	SP001522686	AUIRFR024NTRL	PG-TO252-3
AUIRFZ24NS	SP001517468	AUIRFZ24NS	PG-TO252-3
AUIRFZ24NSTRL	SP001522352	AUIRFZ24NSTRL	PG-TO252-3
AUIRLR120NTRL	SP001516016	AUIRLR120NTRL	PG-TO252-3
AUIRLR2703TRL	SP001521330	AUIRLR2703TRL	PG-TO252-3
AUIRLR3410TR	SP001519922	AUIRLR3410TR	PG-TO252-3